

## General Description

FSMOS<sup>®</sup> MOSFET is based on Oriental Semiconductor's unique device design to achieve low  $R_{DS(ON)}$ , low gate charge, fast switching and excellent avalanche characteristics. The low  $V_{th}$  series is specially optimized for synchronous rectification systems with low driving voltage.

## Features

- Low  $R_{DS(ON)}$  & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



## Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switching mode power supply

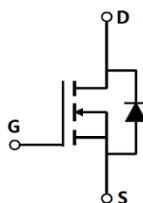
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$	25	V
$I_D$ , pulse	255	A
$R_{DS(ON)}$ , max @ $V_{GS}=10V$	1.9	m $\Omega$
$Q_g$	34.6	nC

## Marking Information

Product Name	Package	Marking
SFSE2R019UNF	PDFN3.3×3.3	SFSE2R019UN

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^{\circ}\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	25	V
Gate-source voltage	$V_{GS}$	$\pm 15$	V
Continuous drain current <sup>1)</sup> , $T_C=25^{\circ}\text{C}$	$I_D$	85	A
Pulsed drain current <sup>2)</sup> , $T_C=25^{\circ}\text{C}$	$I_{D, pulse}$	255	A
Continuous diode forward current <sup>1)</sup> , $T_C=25^{\circ}\text{C}$	$I_S$	85	A
Diode pulsed current <sup>2)</sup> , $T_C=25^{\circ}\text{C}$	$I_{S, pulse}$	255	A
Power dissipation <sup>3)</sup> , $T_C=25^{\circ}\text{C}$	$P_D$	65	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	109	mJ
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^{\circ}\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	1.92	$^{\circ}\text{C/W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	62	$^{\circ}\text{C/W}$

**Electrical Characteristics** at  $T_j=25^{\circ}\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	25			V	$V_{GS}=0\text{ V}, I_D=250\ \mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	1.0		3.0	V	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$
Drain-source on-state resistance	$R_{DS(ON)}$		1.5	1.9	m $\Omega$	$V_{GS}=10\text{ V}, I_D=50\text{ A}$
Drain-source on-state resistance	$R_{DS(ON)}$		2.7	3.0	m $\Omega$	$V_{GS}=4.5\text{ V}, I_D=25\text{ A}$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=15\text{ V}$
				-100		$V_{GS}=-15\text{ V}$
Drain-source leakage current	$I_{DSS}$			1	$\mu\text{A}$	$V_{DS}=25\text{ V}, V_{GS}=0\text{ V}$
Gate resistance	$R_G$		5		$\Omega$	$f=1\text{ MHz}$ , Open drain

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{iss}$		2671		pF	$V_{GS}=0\text{ V}$ , $V_{DS}=25\text{ V}$ , $f=100\text{ kHz}$
Output capacitance	$C_{oss}$		1021		pF	
Reverse transfer capacitance	$C_{rss}$		50.2		pF	
Turn-on delay time	$t_{d(on)}$		21.6		ns	$V_{GS}=10\text{ V}$ , $V_{DS}=20\text{ V}$ , $R_G=2\ \Omega$ , $I_D=40\text{ A}$
Rise time	$t_r$		7.4		ns	
Turn-off delay time	$t_{d(off)}$		51		ns	
Fall time	$t_f$		14.4		ns	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	$Q_g$		34.6		nC	$V_{GS}=10\text{ V}$ , $V_{DS}=20\text{ V}$ , $I_D=40\text{ A}$
Gate-source charge	$Q_{gs}$		8.3		nC	
Gate-drain charge	$Q_{gd}$		4.3		nC	
Gate plateau voltage	$V_{plateau}$		3.8		V	

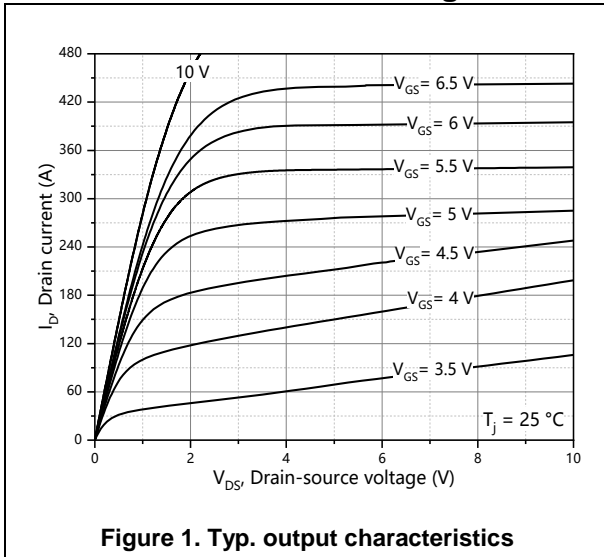
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	$V_{SD}$			1.3	V	$I_S=20\text{ A}$ , $V_{GS}=0\text{ V}$
Reverse recovery time	$t_{rr}$		56		ns	$V_R=20\text{ V}$ , $I_S=40\text{ A}$ , $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	$Q_{rr}$		46		nC	
Peak reverse recovery current	$I_{rrm}$		1.3		A	

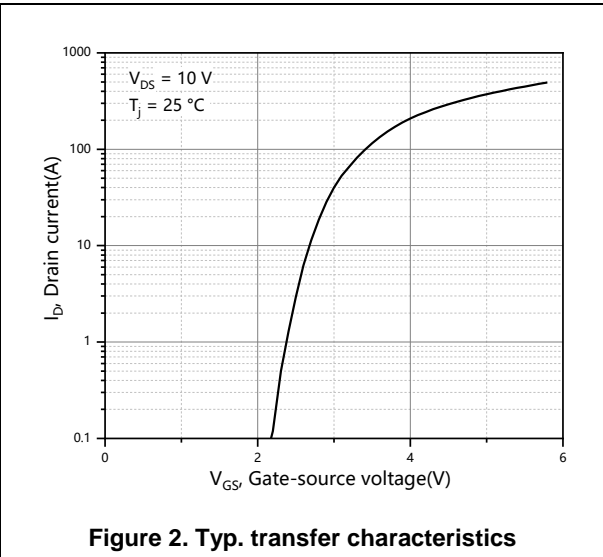
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25\text{ }^\circ\text{C}$ .
- 5)  $V_{DD}=30\text{ V}$ ,  $V_{GS}=10\text{ V}$ ,  $L=0.3\text{ mH}$ , starting  $T_j=25\text{ }^\circ\text{C}$ .

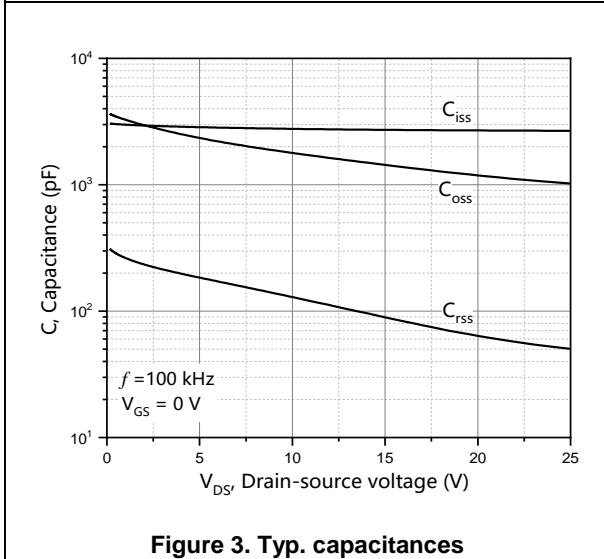
**Electrical Characteristics Diagrams**



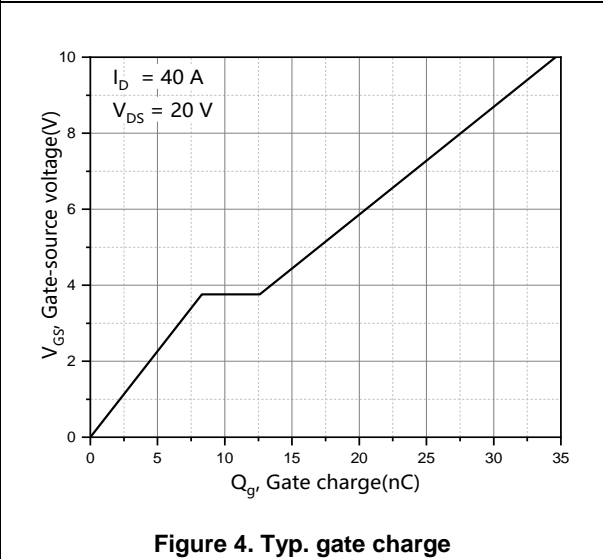
**Figure 1. Typ. output characteristics**



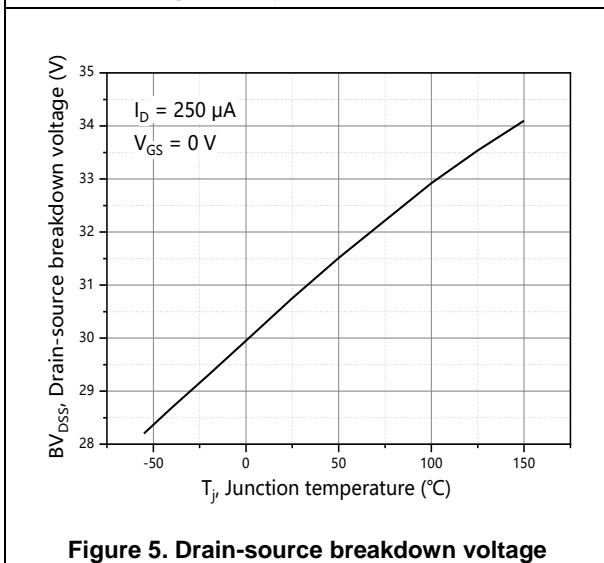
**Figure 2. Typ. transfer characteristics**



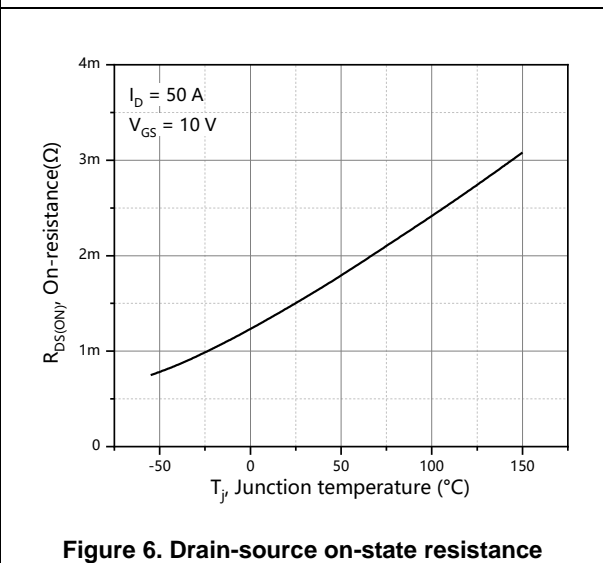
**Figure 3. Typ. capacitances**



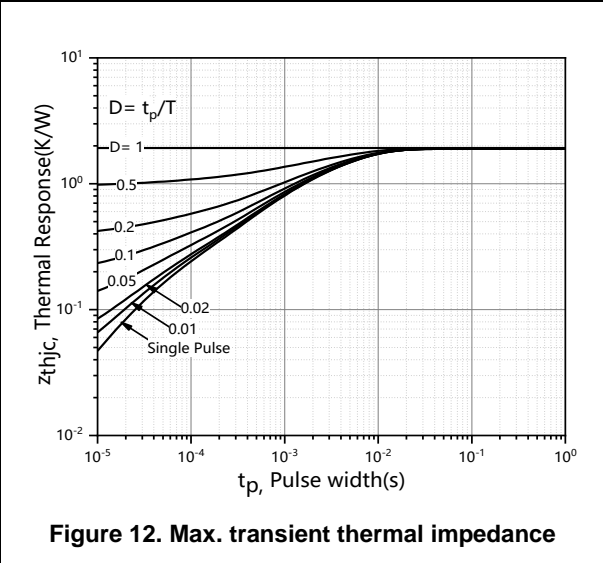
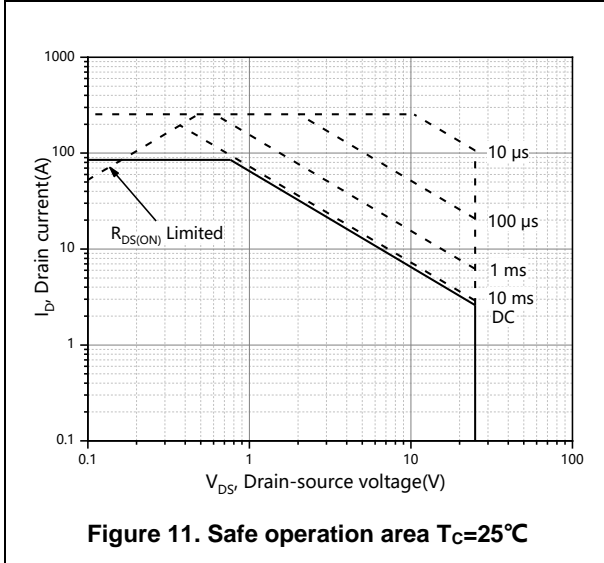
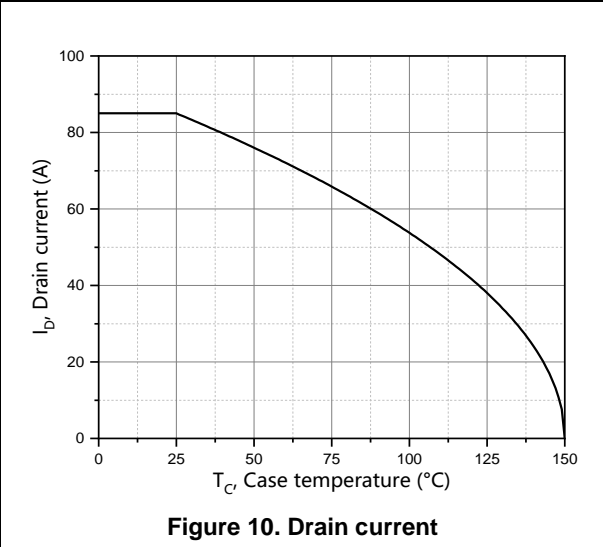
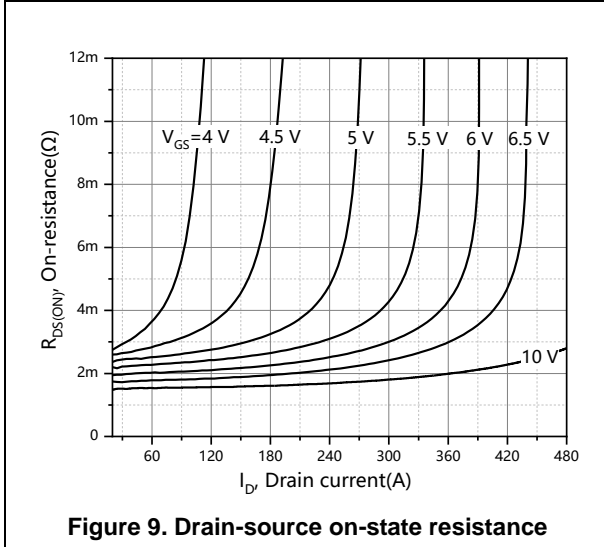
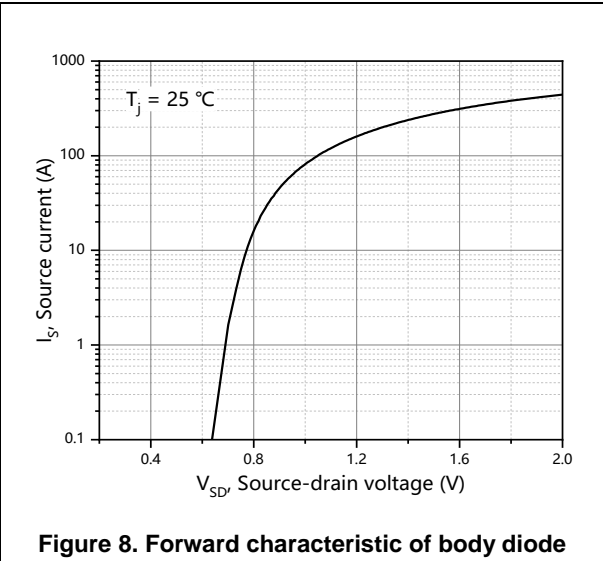
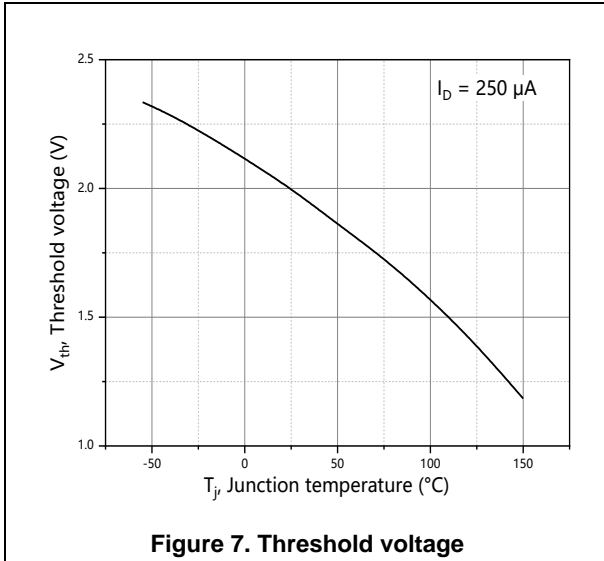
**Figure 4. Typ. gate charge**



**Figure 5. Drain-source breakdown voltage**



**Figure 6. Drain-source on-state resistance**



**Test circuits and waveforms**



**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

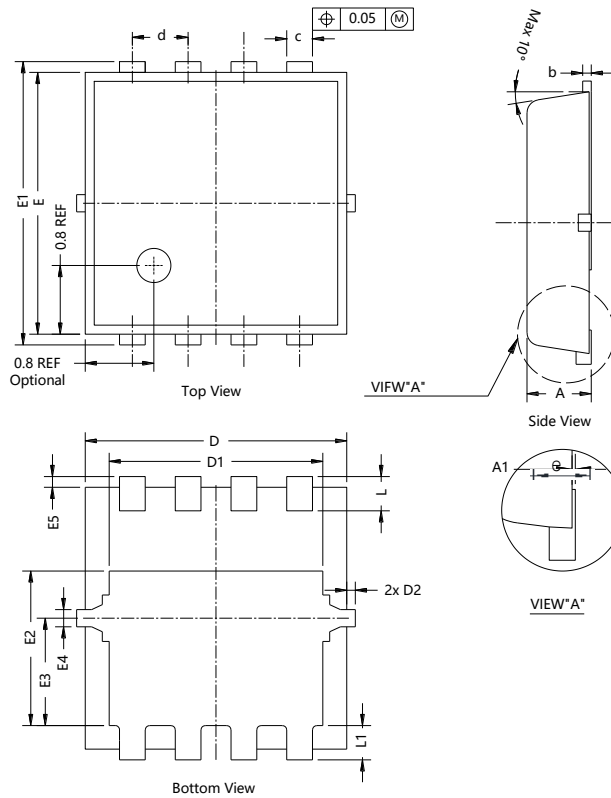


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

**Package Information**



Symbols	mm		
	Min	Nom	Max
A	0.700	0.750	0.800
A1	-	-	0.05
b	0.144	0.152	0.202
c	0.250	0.300	0.350
d	0.65 BSC		
D	2.950	3.050	3.150
D1	2.390	2.490	2.590
D2	-	-	0.125
E	2.950	3.050	3.150
E1	3.200	3.300	3.400
E2	1.700	1.800	1.900
E3	1.150	1.250	1.350
E4	0.150	0.200	0.250
E5	0.075	0.125	0.175
L	0.300	0.400	0.500
L1	0.300	0.400	0.500

Version 1: PDFN3.3×3.3-H package outline dimension



### Ordering Information

Package Type	Units/ Reel	Reels/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
PDFN3.3×3.3-H	5000	2	10000	5	50000
PDFN3.3×3.3-S	5000	1	5000	8	40000

### Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFSE2R019UNF	PDFN3.3×3.3	yes	yes	yes

### Legal Disclaimer

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